

Colloquium



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Packaging Technologies of Integrated Photonics for Quantum Technology

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Thursday 30 November AT 4:10 PM IN NAH 165

The presentation will discuss the current state of integrated photonic packaging from design and prototyping to volume scale up. We will review design rules for packaging and standard packages that result in consistent, high-quality packages at low cost. It will highlight our technologies for efficient optical coupling from chip to chip or chip to fiber array to include spot size converters, and nanoimprinted lenses for surface coupling. We will review applications from Quantum, Lidar and the datacom industry.

Stefan is the VP of Sales for Phix, North America, with experience in Lidar technology at Aurora and laser technology at Fraunhofer and TRUMPF Photonics. He co-founded companies in the laser and renewable energy sectors, engaged in the Alliance for Clean Transportation, and holds a Ph.D. in electrical engineering with numerous patents.